## AEROSPACE DATA EXCHANGE PROGRAM TRANSMITTAL



## **DMSMS NOTICE**

**DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES** 

1. TITLE	2. DOCUMENT NUMBER					
MICROCIRCUIT, DIGITAL	SPO-2014-D-0003					
NAND GATE, MONOLITH	IC SILICON, FAB MIGRATION		3. DATE (Year, Month, Date)			
			2014 February 28			
4. MANUFACTURER NAME AND A	DDRESS	5. MANUFACTURER POINT OF CONTACT	(NAME)			
CAES		MR. TIM MEADE				
4350 CENTENNIAL BOULE	EVARD	6. MANUFACTURER POINT OF CONTACT TELEPHONE				
COLORADO SPRINGS, COLORADO 80907-3486		(719) 594-8048				
		7. MANUFACTURER POINT OF CONTACT EMAIL				
		tim.l.meade@cobhamaes.com				
8. CAGE CODE	9. MANUFACTURER FINAL ORDER DATE	10. PRODUCT IDENTIFICATION CODE	11. BASE PART			
65342	SEE COMMENTS BELOW	C000A	UT54ACS00			
12. BLANK		13. SMD NUMBER	14. DEVICE TYPE DESIGNATOR			
		96512	01			
		15. RHA LEVELS	16. QML LEVEL			
		NON, R, F, G, AND H	Q AND V			
		17. NON QML LEVEL	18. BLANK			
		N/A				
19. COMMENTS						
CAES IS ISSUING THIS DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE AND PRODUCT						
CHANGE NOTIFICATION TO ANNOUNCE THE FOLINDRY MICRATION OF DEVICE TYPE OF FROM 1 21 IM DADIATION						

CAES IS ISSUING THIS DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE AND PRODUCT CHANGE NOTIFICATION TO ANNOUNCE THE FOUNDRY MIGRATION OF DEVICE TYPE 01 FROM 1.2UM RADIATION-HARDENED CMOS TO ON-SEMICONDUCTOR'S 0.6UM C5U COMMERCIAL RADIATION-HARDENED CMOS PROCESS. BECAUSE THE MIGRATED DEVICE IS FORM, FIT, AND FUNCTIONAL TO THE LEGACY DEVICE, IT WILL CONTINUE TO SHIP AS DEVICE TYPE 01.

AS PART OF THIS PROCESS MIGRATION, THE RADIATION HARDNESS ASSURANCE LEVEL "H" AND CASE OUTLINE "C" WILL NO LONGER BE AVAILABLE FROM AN APPROVED SOURCE OF SUPPLY. CAES WILL ACCEPT ORDERS FOR RHA LEVEL "H" AND PACKAGE OUTLINE "C" ON A "FIRST COME, FIRST SERVED" BASIS, THROUGH JUNE 2014 OR UNTIL INVENTORY EXHAUSTS. ADDITIONALLY, DIE SALES AGAINST DIE DETAIL "A" WILL NO LONGER BE AVAILABLE. FUTURE DIE SALES MAY BE ISSUED AGAINST DIE DETAIL "B" OF THE AFFECTED SMD. NOTE: THE NEW DIE SUPPLIED AGAINST DIE DETAIL "B" REQUIRE A SUBSTRATE BIAS TO VSS.

THE MIGRATED DEVICE OFFERING WILL BE AVAILABLE WITH THE FOLLOWING OPTIONS:

SMD #: 5962-96512 DEVICE TYPE: 01

AVAILABLE RHA DESIGNATORS: R (100Krads (Si)), F (300Krads (Si)), G (500Krads (Si))

DEVICE CLASS: Q, V

CASE OUTLINE DESIGNATOR: X (14 LEAD FLAT PACK) OR DIE CODE: 9

LEAD FINISH: A, C, X OR DIÈ DETAIL: B

SHIPMENTS OF THE MIGRATED DEVICE ARE EXPECTED TO BEGIN IN JUNE 2014.

See Continuation on page 2

20. ADEPT REPRESENTATIVE	21. SIGNATURE	22. DATE
Timothy L. Meade	Timothy Meade	28 February, 2014

## Continuation Page 2

Obsolete SMD PINs					Vendor Similar PINs
5962	Н	96512	01	V 9 A	UT54ACS00- VDIE
5962	Н	96512	01	Q 9 A	UT54ACS00- QDIE
5962	Н	96512	01	QCA	UT54ACS00- PQAH
5962	Н	96512	01	QXA	UT54ACS00- UQAH
5962	Н	96512	01	QCC	UT54ACS00- PQCH
5962	Н	96512	01	QXC	UT54ACS00- UQCH
5962	Н	96512	01	V C A	UT54ACS00- PVAH
5962	Н	96512	01	V X A	UT54ACS00- UVAH
5962	Н	96512	01	V C C	UT54ACS00- PVCH
5962	Н	96512	01	V X C	UT54ACS00- UVCH
Replace	SMD	) PINs			Vendor Similar PINs
5962	G	96512	01	Q 9 B	UT54ACS00- QDIE
5962	G	96512	01	QXA	UT54ACS00- UQAG
5962	G	96512	01	QXC	UT54ACS00- UQCG
5962	G	96512	01	V 9 B	UT54ACS00- VDIE
5962	G	96512	01	V X A	UT54ACS00- UVAG
5962	G	96512	01	V X C	UT54ACS00- UVCG